



Material Content Data Sheet



Sales Product Name		1EDI05112AF		Issued		25. September 2017		
MA#		MA001245996						
Package		PG-DSO-8-51		Weight*		80.32 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.899	2.36	2.36	23648	23648
leadframe	inorganic material	phosphorus	7723-14-0	0.008	0.01		103	
	non noble metal	zinc	7440-66-6	0.033	0.04		411	
	non noble metal	iron	7439-89-6	0.660	0.82		8214	
wire	non noble metal	copper	7440-50-8	26.789	33.35	34.22	333541	342269
	noble metal	gold	7440-57-5	0.231	0.29	0.29	2875	2875
	encapsulation	organic material	carbon black	1333-86-4	0.147	0.18		1832
encapsulation	plastics	epoxy resin	-	4.758	5.92		59240	
	inorganic material	silicondioxide	60676-86-0	44.147	54.98	61.08	549646	610718
leadfinish	non noble metal	tin	7440-31-5	0.814	1.01	1.01	10133	10133
plating	noble metal	silver	7440-22-4	0.095	0.12	0.12	1186	1186
glue	plastics	acrylic resin	-	0.162	0.20		2018	
	noble metal	silver	7440-22-4	0.575	0.72	0.92	7153	9171
*deviation	< 10%					Sum in total:	100.00	1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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